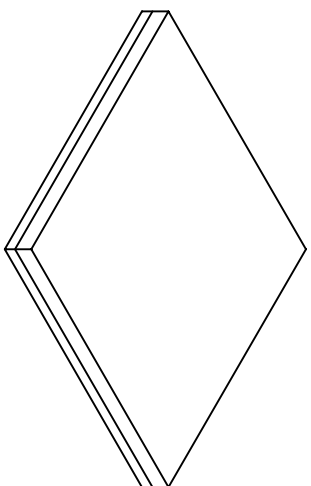


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REV.	DESCRIPTION	DATE	DESIGNED BY	CHECKED BY
00	INITIAL RELEASE DCN NO.C02135	06/28/97	H.T.B.	E.S.K.
01	REVISED DIMENSIONS PER DCN# C02757	12/12/97	SHK	H.L.E.
02	REVISED TOLERANCE PER DCN# C04351	08/08/98	E.B.	H.L.E.



7. REFERENCE SPECIFICATIONS:
 A. AAWT SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
 B. AAWT SPEC #001-0519-2082: MARKING.

- 6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
- 5. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMPS IS 64.

- 4. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 8 X 8.
 - 3. THE BASIC SOLDER BUMP GRID PITCH IS 0.80mm.
 - 2. THE BASIC SOLDER BUMP GRID PITCH IS 0.80mm.
 - 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		APPROXIMATE DATE		DATE		DATE		DATE	
DECIMAL	ANGULAR	APPROXIMATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE
XX ±0.10	±1°	APPROXIMATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE
XXX ±0.05		APPROXIMATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE
XXXX ±0.03		APPROXIMATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE
DO NOT SCALE DRAWING		APPROXIMATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE